



US00D755135S

(12) **United States Design Patent**
Feng

(10) **Patent No.:** **US D755,135 S**

(45) **Date of Patent:** **** *May 3, 2016**

(54) **LIGHT EMITTING DIODE CHIP**

(71) Applicant: **Formosa Epitaxy Incorporation,**
Taoyuan County (TW)
(72) Inventor: **Hui-Ching Feng,** Taoyuan County (TW)
(73) Assignee: **Formosa Epitaxy Incorporation,**
Taoyuan (TW)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/489,895**

(22) Filed: **May 5, 2014**

(30) **Foreign Application Priority Data**

Jan. 28, 2014 (TW) 103300564

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D21/486, 501, 503; D25/152,
D25/155, 160, 163; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/0079; H01L 33/04; H01L 33/08;
H01L 33/10; H01L 33/20; H01L 33/38;
H01L 33/42; H01L 33/4448; H01L 33/483;
H01L 33/486; H01L 24/06; H01J 3/021;
H01S 5/34; F21K 9/00; F21K 9/30; F21K
9/54; B82Y 20/00; B82Y 40/00
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2,280,631	A *	4/1942	Coffey	181/293
4,032,944	A *	6/1977	van Dongen et al.	257/88
4,189,027	A *	2/1980	Dean et al.	181/286
D410,973	S *	6/1999	Jensen	D21/486
D412,189	S *	7/1999	Poulsen	D21/502
6,012,543	A *	1/2000	Shimpo et al.	181/286
6,764,196	B2 *	7/2004	Bailey	362/147
6,870,125	B2 *	3/2005	Doi et al.	219/121.6
D510,912	S *	10/2005	Asakawa	D13/180
D511,329	S *	11/2005	Suenaga	D13/180
7,621,654	B2 *	11/2009	Nishimoto et al.	362/241
7,690,809	B2 *	4/2010	Tsai et al.	362/147
D616,506	S *	5/2010	Kossmann	D21/501
7,710,014	B2 *	5/2010	Lee et al.	313/497
7,786,491	B2 *	8/2010	Ueda et al.	257/81
D646,647	S *	10/2011	Chen et al.	D13/180
8,415,689	B2 *	4/2013	Lim	257/91
8,569,739	B2 *	10/2013	Kim et al.	257/14
8,704,249	B2 *	4/2014	Kamiya et al.	257/91
8,749,263	B2 *	6/2014	Ohta et al.	324/762.01
D725,052	S *	3/2015	Chen et al.	D13/180
2003/0001477	A1 *	1/2003	Sasaguri	313/310

(Continued)

Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — Jianq Chyun IP Office

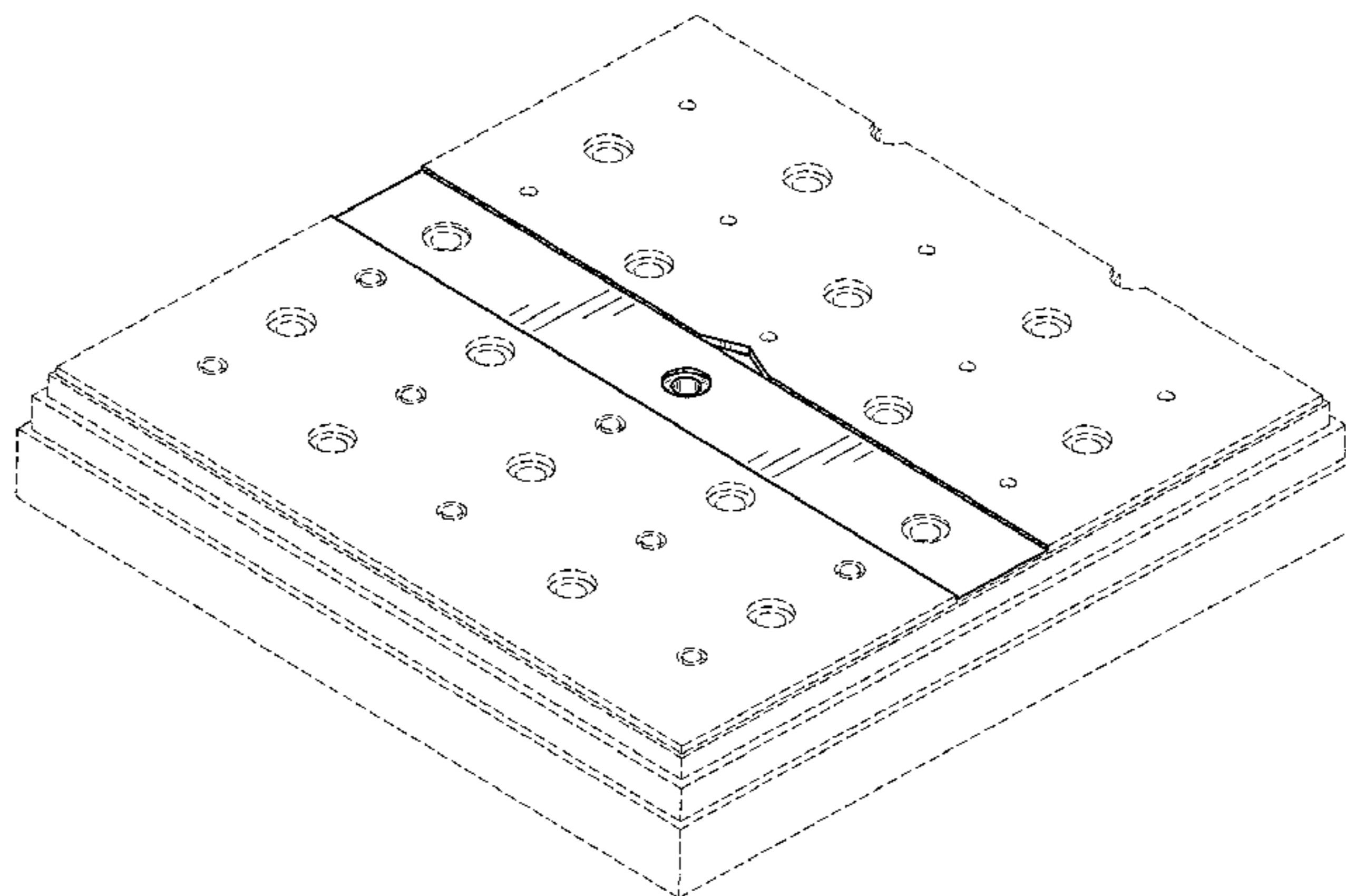
(57) **CLAIM**

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing an embodiment of my new design; FIG. 2 is a front view of the embodiment; FIG. 3 is a rear view of the embodiment; FIG. 4 is a left side view of the embodiment; FIG. 5 is a right side view of the embodiment; FIG. 6 is a top view of the embodiment; and, FIG. 7 is a bottom view of the embodiment. The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

2005/0184647	A1 *	8/2005	Chang	313/497	2008/0116782	A1 *	5/2008	Kim et al.	313/496
2006/0022575	A1 *	2/2006	Ryu et al.	313/495	2010/0208761	A1 *	8/2010	Coleman et al.	372/45.01
2006/0160409	A1 *	7/2006	Shimizu et al.	439/490	2011/0220872	A1 *	9/2011	Fukunaga et al.	257/13
2006/0208628	A1 *	9/2006	Lee	313/497	2011/0291070	A1 *	12/2011	Won et al.	257/13
2006/0261725	A1 *	11/2006	Lee	313/495	2011/0291120	A1 *	12/2011	Tak et al.	257/88
2007/0096624	A1 *	5/2007	Lee et al.	313/496	2012/0056232	A1 *	3/2012	Fujimoto et al.	257/99
2007/0176206	A1 *	8/2007	Choi et al.	257/198	2012/0153260	A1 *	6/2012	Kim et al.	257/14
2008/0030117	A1 *	2/2008	Chen et al.	313/311	2013/0285105	A1 *	10/2013	Wei et al.	257/99
						2013/0321902	A1 *	12/2013	Choi	359/344
						2014/0191650	A1 *	7/2014	Lee et al.	313/310
						2014/0353709	A1 *	12/2014	Lee et al.	257/99

* cited by examiner

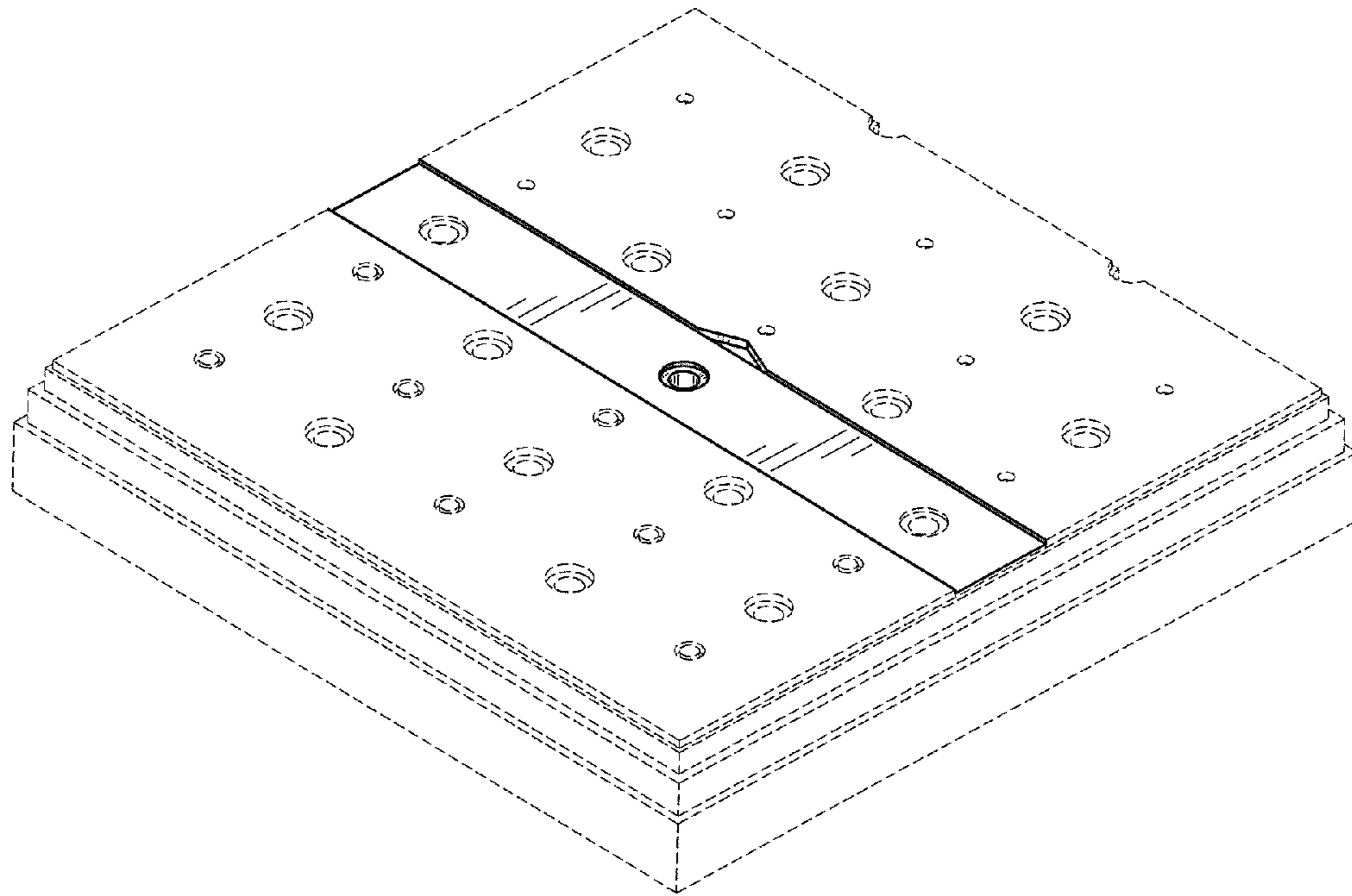


FIG. 1

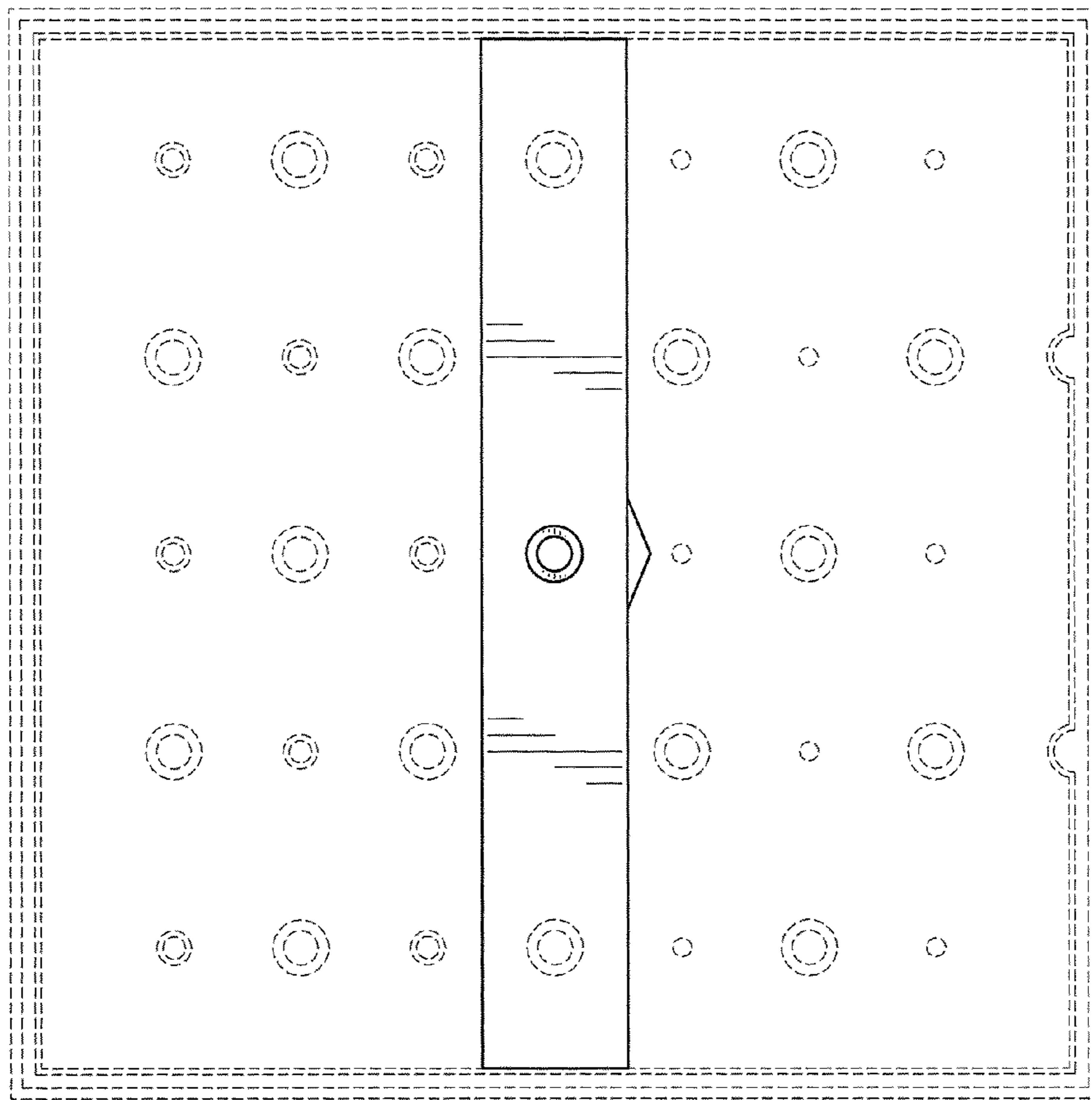


FIG. 2

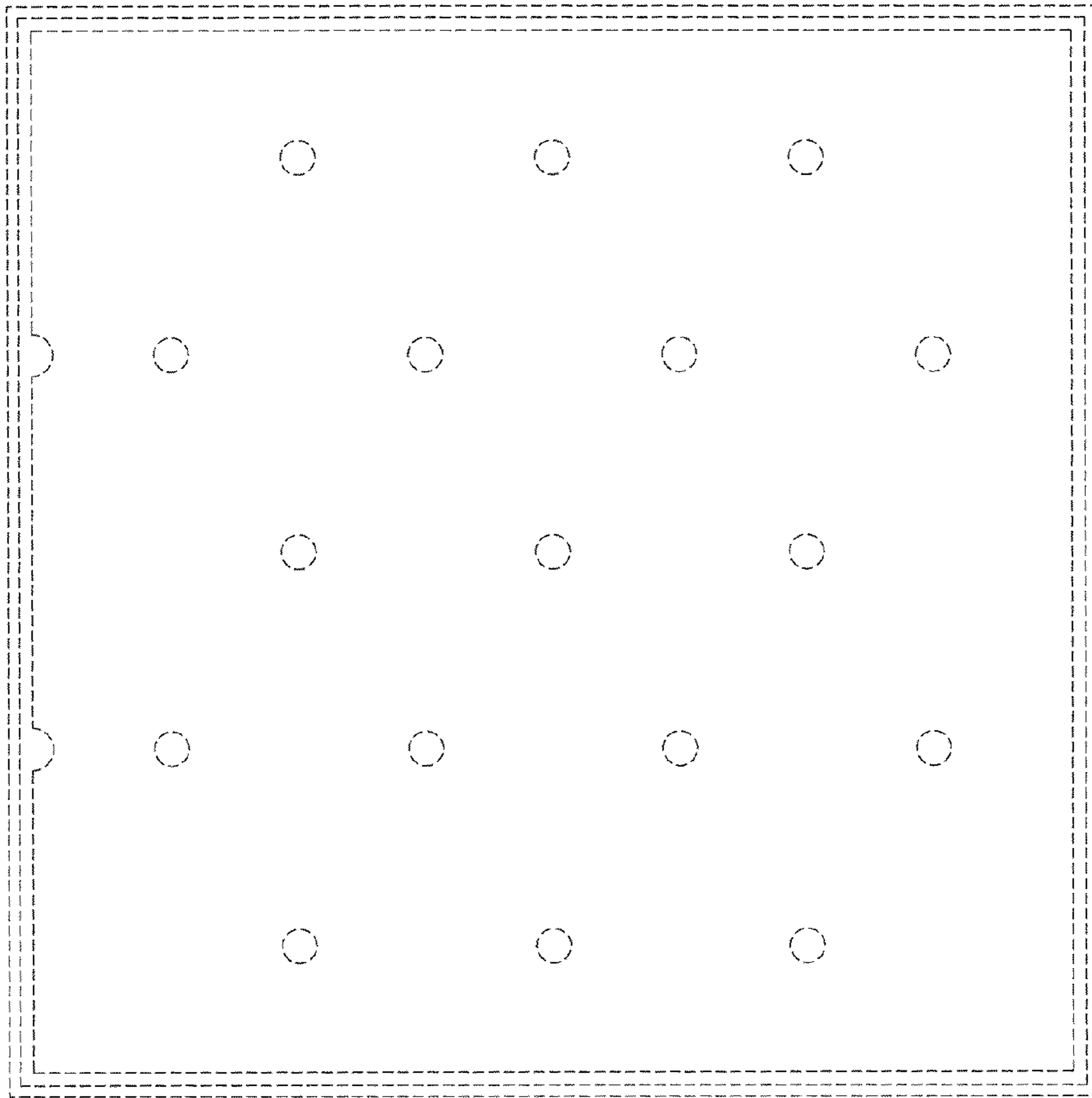


FIG. 3

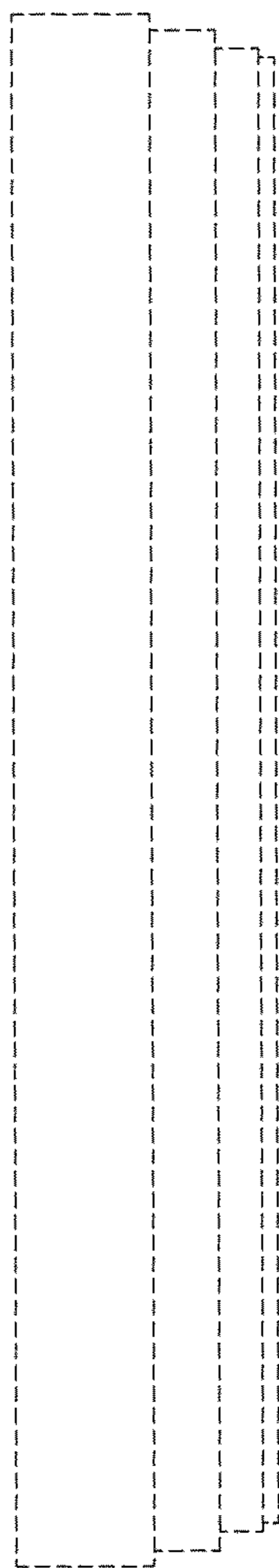


FIG. 4

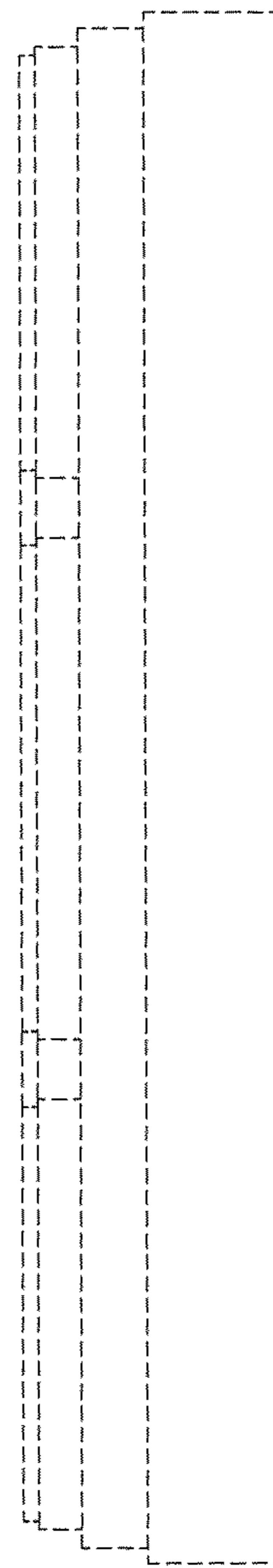


FIG. 5

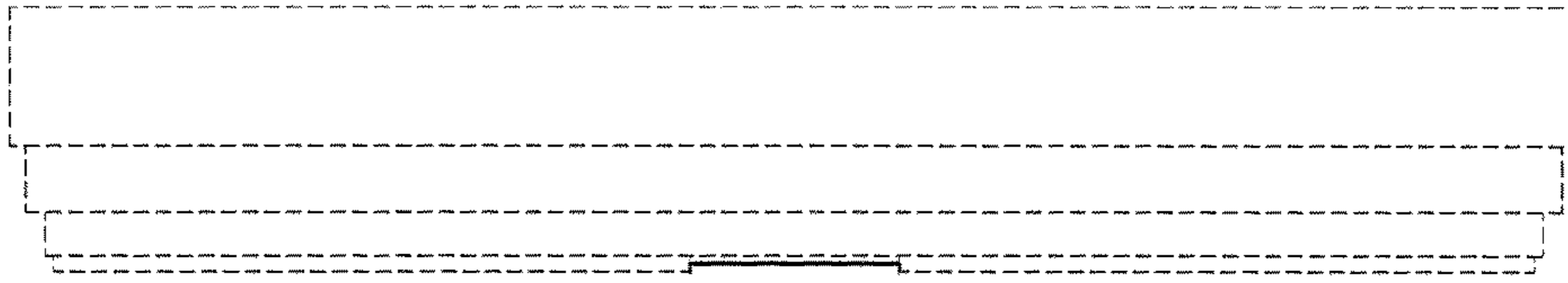


FIG. 6

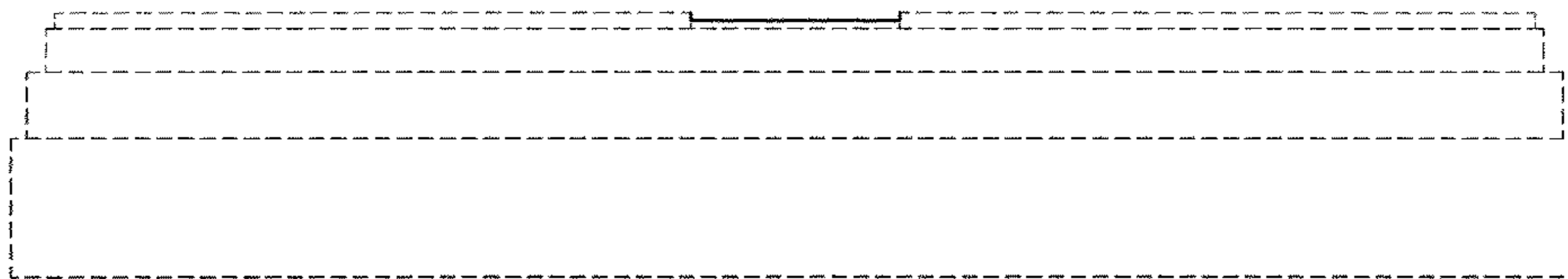


FIG. 7